

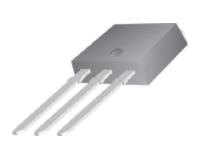
P-Channel 30-V (D-S) MOSFET

These miniature surface mount MOSFETs utilize High Cell Density process. Low $r_{DS(on)}$ assures minimal power loss and conserves energy, making this device ideal for use in power management circuitry. Typical applications are PWMDC-DC converters, power management in portable and battery-powered products such as computers, printers, battery charger, telecommunication power system, and telephones power system.

•	Low $r_{DS(\text{on})}$ Provides Higher Efficiency and
	Extends Battery Life

- Miniature TO-251 Surface Mount Package Saves Board Space
- High power and current handling capability
- Extended VGS range (±25) for battery pack applications

PRODUCT SUMMARY				
V _{DS} (V)	$r_{\mathrm{DS}(\mathrm{on})} \mathrm{m}(\Omega)$	$I_{D}(A)$		
-30	$59 @ V_{GS} = -10V$	24		
-30	$95 @ V_{GS} = -4.5V$	19		





ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C UNLESS OTHERWISE NOTED)					
Parameter			Maximum	Units	
Drain-Source Voltage			-30	V	
Gate-Source Voltage		V_{GS}	±25	[
Continuous Drain Current ^a	$T_A=25^{\circ}C$	I_D	24	Α	
Pulsed Drain Current ^b		I_{DM}	±40	A	
Continuous Source Current (Diode Conduction) ^a		I_S	-30	A	
Power Dissipation ^a	$T_A=25^{\circ}C$	P_{D}	50	W	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 175	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Maximum	Units	
Maximum Junction-to-Ambient ^a	$R_{ heta JA}$	50	°C/W	
Maximum Junction-to-Case	$R_{ heta JC}$	3.0	°C/W	

Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

Parameter	Symbol	Test Conditions	Limits			Unit	
rarameter			Min	Тур	Max	Umi	
Static							
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = -250 \text{ uA}$	-1				
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			±100	nA	
Zero Gate Voltage Drain Current	Ţ	$V_{DS} = -24 \text{ V}, V_{GS} = 0 \text{ V}$			-1	uA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -24 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55^{\circ}\text{C}$			-5	uA	
On-State Drain Current ^A	I _{D(on)}	$V_{DS} = -5 \text{ V}, V_{GS} = -10 \text{ V}$	-41			Α	
Drain-Source On-Resistance ^A		$V_{GS} = -10 \text{ V}, I_D = -24 \text{ A}$			59	m0	
Drain-Source On-Resistance	r _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -19 \text{ A}$			95	mΩ	
Forward Tranconductance ^A	${ m g}_{ m fs}$	$V_{DS} = -15 \text{ V}, I_D = -24 \text{ A}$		31		S	
Diode Forward Voltage	V_{SD}	$I_{S} = -41 \text{ A}, V_{GS} = 0 \text{ V}$		-0.7		V	
Dynamic ^b							
Total Gate Charge	Q_{g}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V},$ $I_{D} = -24 \text{ A}$		6.4		пС	
Gate-Source Charge	Q_{gs}			1.9			
Gate-Drain Charge	Q_{gd}			2.5			
Switching							
Turn-On Delay Time	$t_{d(on)}$			10			
Rise Time	$t_{\rm r}$	$V_{DD} = -15 \text{ V}, R_L = 15 \Omega, ID = -24$		2.8		nS	
Turn-Off Delay Time	$t_{d(off)}$	A, $VGEN = -10 \text{ V}$, $RG = 6\Omega$		53.6			
Fall-Time	$t_{\rm f}$			46		1	

Notes

- a. Pulse test: PW <= 300us duty cycle <= 2%.
- b. Guaranteed by design, not subject to production testing.